



UF1404

Preliminary

Power MOSFET

162A, 40V N-CHANNEL POWER MOSFET

DESCRIPTION

The UTC **UF1404** is a N-channel enhancement power MOSFET using UTC's advanced technology to provide the customers with perfect $R_{DS(ON)}$ and high switching speed.

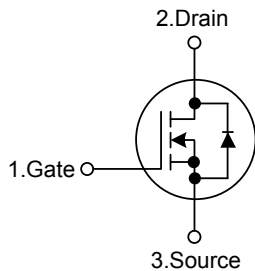
The UTC **UF1404** is suitable for all commercial-industrial applications at power dissipation levels to approximately 50 watts, etc.

FEATURES

* $R_{DS(ON)} = 4m\Omega @ V_{GS} = 10V, I_D = 95A$

* High Switching Speed

SYMBOL

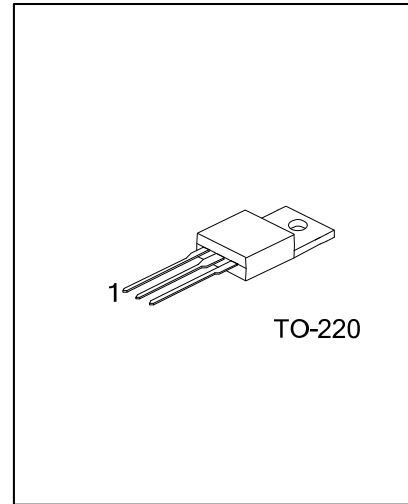


ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
UF1404L-TA3-T	UF1404G-TA3-T	TO-220	G	D	S	Tube

Note: Pin Assignment: G: Gate D: Drain S: Source

UF1404L-TA3-T 	(1) T: Tube (2) TA3: TO-220 (3) G: Halogen Free, L: Lead Free
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■ ABSOLUTE MAXIMUM RATINGS ($T_J=25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	40	V
Gate-Source Voltage		V_{GSS}	± 20	V
Drain Current	Continuous ($V_{GS}=10\text{V}$)	$T_C=25^\circ\text{C}$	162 (Note 5)	A
		$T_C=100^\circ\text{C}$	115 (Note 5)	A
	Pulsed (Note 2)	$T_C=25^\circ\text{C}$	I_{DM}	650
Avalanche Current (Note 2)		I_{AR}	95	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	519	mJ
	Repetitive (Note 2)	E_{AR}	20	mJ
Peak Diode Recovery dv/dt (Note 3)		dv/dt	5.0	V/ns
Power Dissipation ($T_C=25^\circ\text{C}$)		P_D	200	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55~+150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive rating: pulse width limited by maximum junction temperature

3. Starting $T_J=25^\circ\text{C}$, $L=0.12\text{mH}$, $R_G=25\Omega$, $I_{AS}=95\text{A}$

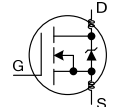
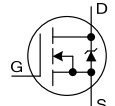
4. $I_{SD}\leq 95\text{A}$, $di/dt\leq 150\text{A}/\mu\text{s}$, $V_{DD}\leq BV_{DSS}$, $T_J\leq 175^\circ\text{C}$

5. Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A

■ THERMAL CHARACTERISTICS

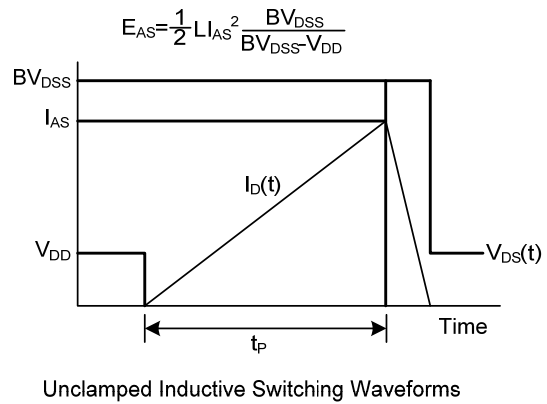
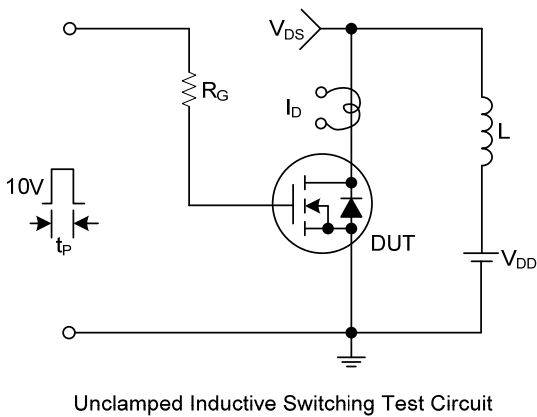
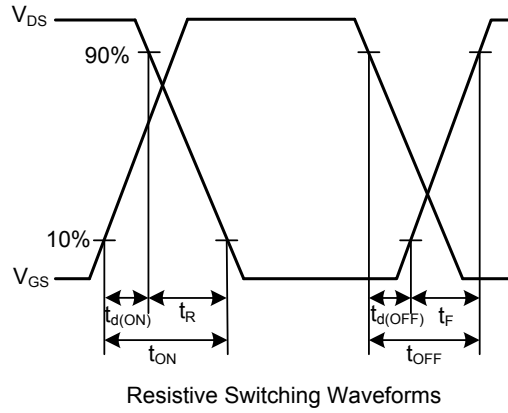
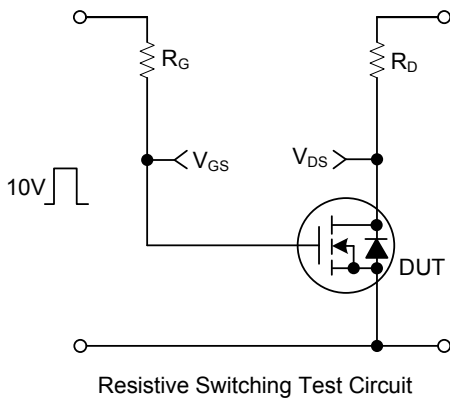
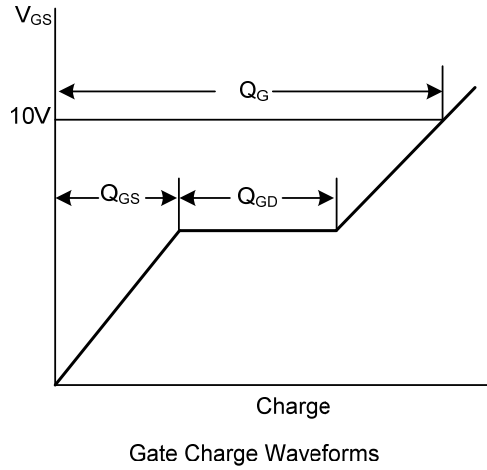
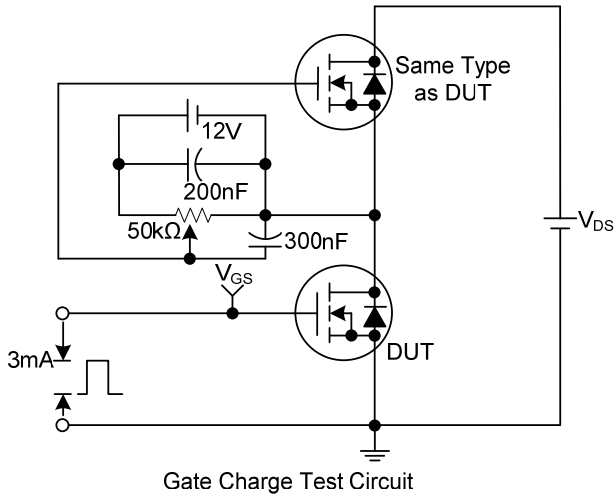
PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	62	$^\circ\text{C}/\text{W}$
Junction to Case	θ_{JC}	0.625	$^\circ\text{C}/\text{W}$

■ ELECTRICAL CHARACTERISTICS ($T_J=25^\circ\text{C}$, unless otherwise specified)

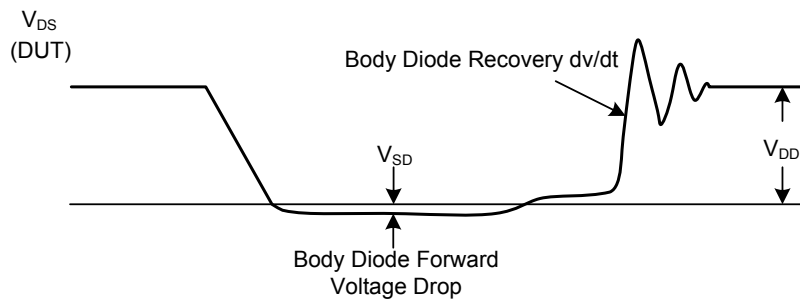
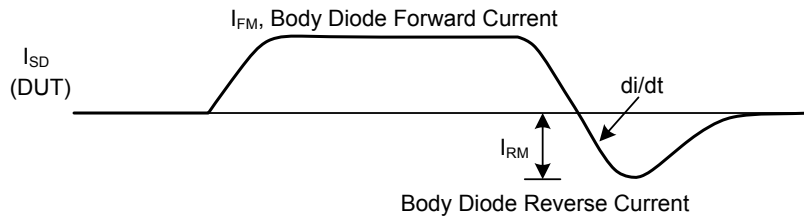
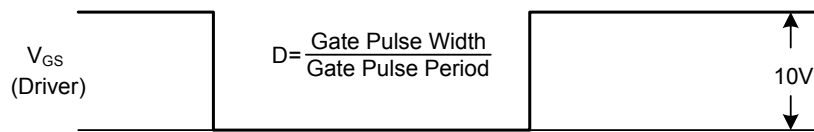
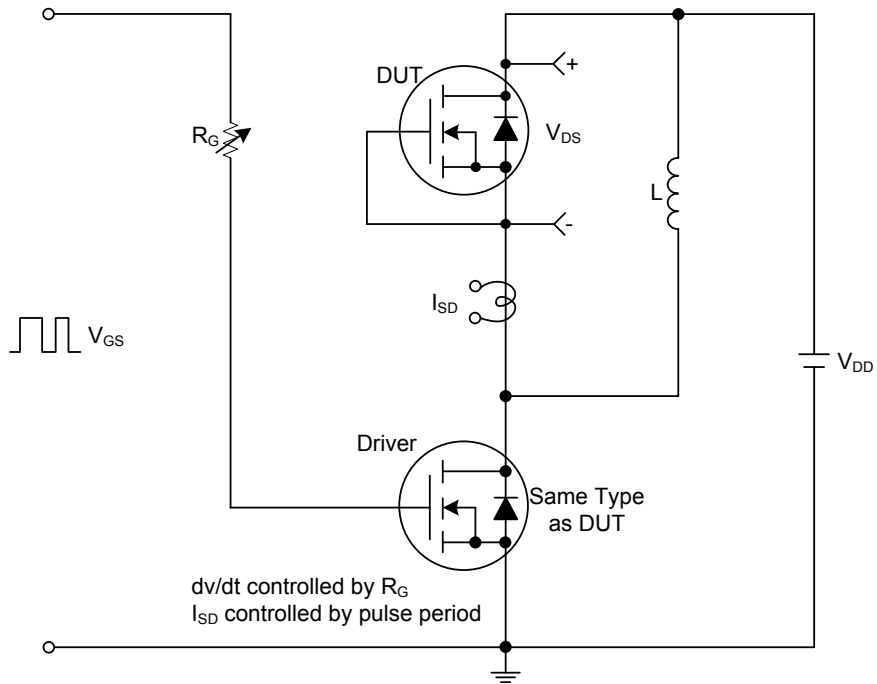
PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40			V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to 25°C , $I_D=1\text{mA}$		0.036		$V/^\circ\text{C}$
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			20	μA
		$V_{DS}=32V, V_{GS}=0V, T_J=150^\circ\text{C}$			250	μA
Gate- Source Leakage Current	Forward	$V_{GS}=+20V$			+200	nA
	Reverse	$V_{GS}=-20V$			-200	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=95A$ (Note 2)		3.5	4	m Ω
DYNAMIC PARAMETERS						
Input Capacitance	C_{ISS}	$V_{GS}=0V, V_{DS}=25V, f=1.0\text{MHz}$		7.36		nF
Output Capacitance	C_{OSS}			1.68		nF
Reverse Transfer Capacitance	C_{RSS}			0.24		nF
SWITCHING PARAMETERS						
Total Gate Charge	Q_G	$I_D=95A, V_{DS}=32V, V_{GS}=10V$ (Note 2)		160	200	nC
Gate to Source Charge	Q_{GS}			35		nC
Gate to Drain Charge	Q_{GD}			42	60	nC
Turn-ON Delay Time	$t_{D(ON)}$	$V_{DD}=20V, I_D=95A, R_G=2.5\Omega,$ $R_D=0.21\Omega$ (Note 2)		17		ns
Rise Time	t_R			140		ns
Turn-OFF Delay Time	$t_{D(OFF)}$			72		ns
Fall-Time	t_F			26		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS						
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25in.) from package and center of die contact			4.5	nH
Internal Source Inductance	L_S					7.5
Maximum Body-Diode Continuous Current (Note 4)	I_S	MOSFET symbol showing the integral reverse p-n junction diode.			162	A
Maximum Body-Diode Pulsed Current (Note 1)	I_{SM}					650
Drain-Source Diode Forward Voltage	V_{SD}	$I_S=95A, V_{GS}=0V, T_J=25^\circ\text{C}$ (Note 2)			1.3	V
Body Diode Reverse Recovery Time	t_{RR}	$I_F=95A, di/dt=100A/\mu s,$		71	110	ns
Body Diode Reverse Recovery Charge	Q_{RR}	$T_J=25^\circ\text{C}$ (Note 2)		180	270	μC

- Notes: 1. Repetitive rating: pulse width limited by maximum junction temperature
 2. Pulse width $\leq 300\mu s$, Duty cycles $\leq 2\%$
 3. C_{OSS} eff. is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 80% V_{DSS}
 4. Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A

■ TEST CIRCUITS AND WAVEFORMS



■ TEST CIRCUITS AND WAVEFORMS(Cont.)



Peak Diode Recovery dv/dt Test Circuit and Waveforms

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